

Document No	TRLP-250S001B
Issued date	2007/3/8
page	1/6

1. Scope:

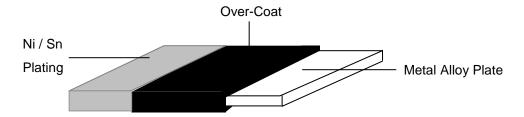
This specification applied to the products of current sensing resistor of metal foil for Lead-Free RLP series manufactured by TA-I TECHNOLOGY CO.,LTD.

2. Type Designation:

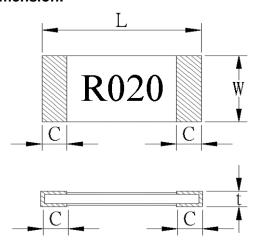
<u>RLP</u> Item	<u>25</u> Series No	<u>F</u> Resistance tolerance	<u>E</u> Packaging	<u>G</u> Power Rating	<u>R020</u> Resistance	
	25:2512	F:±1%	E: Embossed Tape	C=1W	e.g :	
	(6432)	G: <u>±</u> 2%		E=2W	R020=20m Ω	
		J:±5%		G=3W		

3. Construction and Dimension :

3.1 Construction:



3.2 Dimension:



Unit: mm

Style	L	W	С	t	Material
RLP25	6.4±0.2	3.2±0.2	0.9±0.2	0.7.10.00	Metal: Copper-Nickel Alloy or Copper-manganese Alloy Over Coating: molding Compound UL-94 grade



Document No	TRLP-250S001B
Issued date	2007/3/8
page	2/6

4. Features:

Туре	RLP25
Power Rating	1W 、 2 W 、 3W
Resistance Value	10~100mΩ
Operation Temperature Range	-55°C ~+170°C
Temperature Coefficient of Resistance	75ppm /°C
Tolerance	±1%,±2%,±5%
Insulation Resistance	Over 100M Ω
Maximum Working Voltage(V)	(P*R) ^{1/2}

5. Reliability Tests:

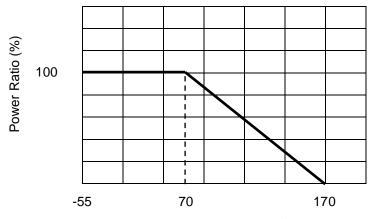
Test Items	Condition of Test	Test Limits
Temperature Coefficient of Resistance	+25℃ ~+125℃	Refer 4.0
Load Life	1000hours at rated power, 70°C, 1.5hours "ON", 0.5hour "OFF"	±1%
Short Time Overload	5 X rated power for 5s	$\pm 0.5\%$ (For 40-100 m Ω rated power x 2.5 for 5 s)
Moisture no Load	85℃, 85%RH, 1000hrs	±0.5%
Temperature cycle	-40°C & +125°C, 1000cycle, 15min per extreme condition	±0.5%
Resistance to Soldering Heat	260±5°C for20±1 sec	±0.5%
Solderability	245±5°C, 2±0.5sec	At least 95% of surface area of electrode shall be covered with new solder
High Temperature Exposure	170℃, 1000hrs	±0.5%
Low Temperature Storage	-55℃ , 1000hrs	±0.5%
Substrate Bending	Bending width 2mm, Epoxy thickness 1.6mm, Fulcrums distance 90mm	±1.0%
Insulation Resistance	100V DC for 1 minute	>100 MΩ

Note:2&3 watts total Solder pad and trace size of $300 \mathrm{mm}^2$



Document No	TRLP-250S001B
Issued date	2007/3/8
page	3/6

5.1Derating Curve



Ambient Temperature (°C)

5.2 Rated Voltage

The rated voltage is calculated by the following Formula:

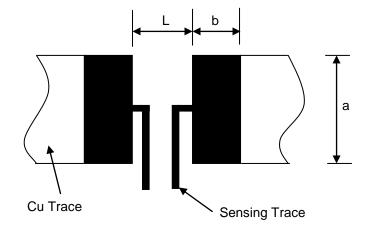
V=√ P*R

V:Rated Voltage(V)

P:Rated Power(W)

R:Resistance Value(Ω)

6. Recommended Solder Pad Dimension



Resistance Range (Ω)	а	b	L
0.010-0.100	4.0	2.1	4.1

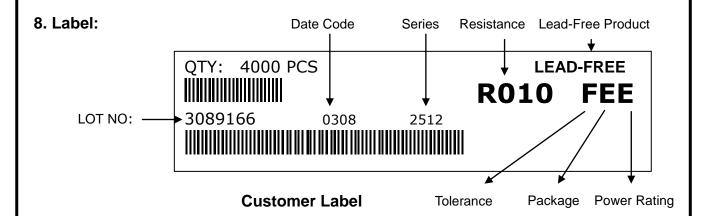
Unit:mm



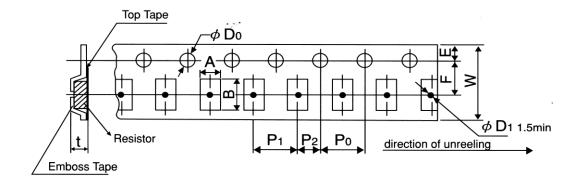
Document No	TRLP-250S001B
Issued date	2007/3/8
page	4/6

7. Number of Package:

4000 Pieces / package



9. Taping

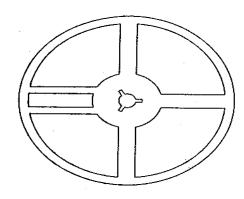


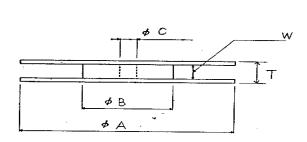
Packing	Type	Α	В	W	F	Е	P ₁	P ₂	P_0	D_0	Т
Emboss	RLP25	3.6±0.2	6.9±0.2	12.±0.2	5.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.05	φ 1.5 (+0.1/-0)	1.2±0.15



Document No	TRLP-250S001B
Issued date	2007/3/8
page	5/6

10. Reel Specification

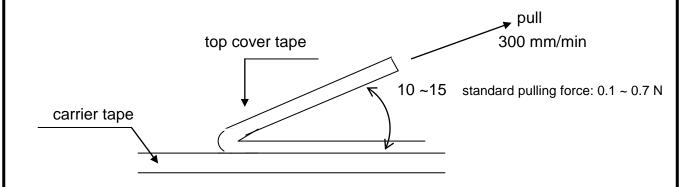




Series	Series ϕ A		ϕ B ϕ C W		Т
RLP 25	180 -3	60 min	13.0±1.0	13.0±1.0	15.4 <u>+</u> 2.0

11. Peeling Strength of Top Cover Tape

Test Condition: 0.1 to 0.7 N at a peel-off speed of 300 mm / min.



12. Storage Conditions:

Temperature: 5°C ~35°C ,Humidity:40%~75%

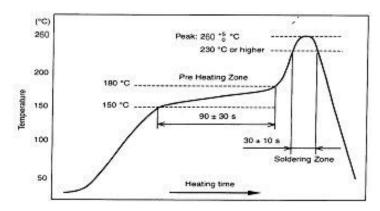
13. Shelf Life:

2 years from manufacturing date.



Document No	TRLP-250S001B
Issued date	2007/3/8
page	6/6

14. Recommend IR - Reflow profile: (solder: Sn96.5 / Ag3 / Cu0.5)



Peak : 260 $^{+5}_{-0}$ °C , 5 sec

Pre – heat zone : 150 to 180 $^{\circ}$ C, 90 \pm 30 sec Soldering zone : 230 $^{\circ}$ C or higher , 30 \pm 10 sec

Iron Solder:350 \pm 10 $^{\circ}$ C , 3+1/-0 sec

15. ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in approval sheet.